

=> file reg
FILE 'REGISTRY' ENTERED AT 14:50:54 ON 18 MAR 2003
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STRUCTURE FILE UPDATES: 17 MAR 2003 HIGHEST RN 499763-93-8
DICTIONARY FILE UPDATES: 17 MAR 2003 HIGHEST RN 499763-93-8

TSCA INFORMATION NOW CURRENT THROUGH MAY 20, 2002

Please note that search-term pricing does apply when
conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Experimental and calculated property data are now available. See HELP
PROPERTIES for more information. See STNote 27, Searching Properties
in the CAS Registry File, for complete details:
<http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf>

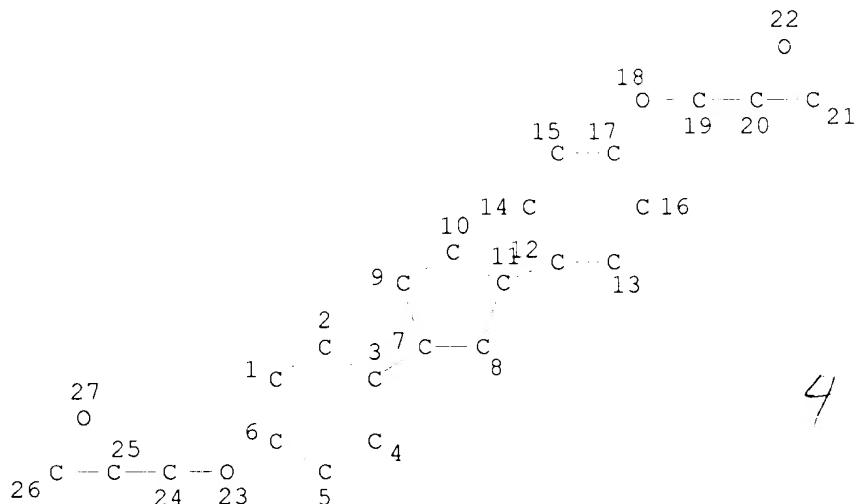
=> file hcaplus
FILE 'HCAPLUS' ENTERED AT 14:50:58 ON 18 MAR 2003
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FILE COVERS 1907 - 18 Mar 2003 VOL 138 ISS 12
FILE LAST UPDATED: 17 Mar 2003 (20030317/ED)

This file contains CAS Registry Numbers for easy and accurate
substance identification.

=> d que
L21 STR



4 structures from this group

NODE ATTRIBUTES:
 DEFAULT MLEVEL IS ATOM
 DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:
 RING(S) ARE ISOLATED OR EMBEDDED
 NUMBER OF NODES IS 27

STEREO ATTRIBUTES: NONE
 L23 4 SEA FILE=REGISTRY SSS FUL L21
 L24 1 SEA FILE=HCAPLUS ABB=ON L23

1 CA structure

=> d l24 all hitstr

L24 ANSWER 1 OF 1 HCAPLUS COPYRIGHT 2003 ACS
 AN 1998:388488 HCAPLUS
 DN 129:55007
 TI Cyclopentylene compounds and intermediates therefor, epoxy resin composition, molding material, and resin-sealed electronic device using the same
 IN Sue, Haruaki; Hagiwara, Shinsuke; Furusawa, Fumio; Akagi, Seiichi; Kobayashi, Akihiro; Yokoyama, Hideki
 PA Hitachi Chemical Company, Ltd., Japan; Sue, Haruaki; Hagiwara, Shinsuke; Furusawa, Fumio; Akagi, Seiichi; Kobayashi, Akihiro; Yokoyama, Hideki
 SO PCT Int. Appl., 79 pp.
 CODEN: PIXXD2
 DT Patent
 LA Japanese
 IC ICM C07C039-17
 ICS C07C039-23; C07C039-42; C08L063-00; C08K005-04; H01L023-29
 CC 37-3 (Plastics Manufacture and Processing)
 Section cross-reference(s): 25, 38, 76
 FAN.CNT 1

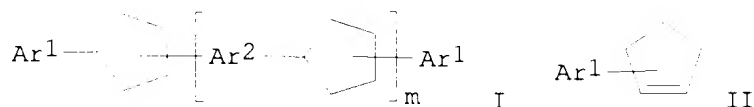
applicant

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 9823568	A1	19980604	WO 1997-JP4373	19971201

W: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, IL, IS, JP, KE, KG, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM
 RW: GH, KE, LS, MW, SD, SZ, UG, ZW, AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG

AU 9851923	A1	19980622	AU 1998-51923	19971201
JP 3199754	B2	20010820	JP 1998-524536	19971201
KR 2000057287	A	20000915	KR 1999-704695	19990527
US 6329492	B1	20011211	US 1999-319487	19990813
US 2002065386	A1	20020530	US 2001-986630	20011109
PRAI JP 1996-320118	A	19961129		
JP 1997-43512	A	19970227		
WO 1997-JP4373	W	19971201		
US 1999-319487	A1	19990813		

GI



AB The cyclopentylene compds. I are suitable for use as a sealing material for electronic devices, have a high Tg, a low hygroscopicity, and high adhesive properties, and are highly flowable and are prepd. from intermediates II, wherein m > 0; Ar1, Ar2 = phenol residue, a naphthol residue, or a fluorene deriv. residue, contg. hydroxy or glycidyloxy group. 1,3-Bis[4-(2,3-epoxypropoxy)-3,5-dimethylphenyl]cyclopentane prepd. from cyclopentadiene and 2,6-dimethylphenyl showed viscosity 0.05 P, compared with 0.1 for YX-4000H.

ST cyclopentylene epoxy resin potting compd; molding cyclopentylene epoxy resin

IT Epoxy resins, uses
 RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
 (bromine-contg.; cyclopentylene compds. and intermediates therefor, epoxy resin compn., molding material, and resin-sealed electronic device using the same)

IT Crosslinking agents
 Electronic packaging process
 Potting compositions
 Semiconductor devices
 (cyclopentylene compds. and intermediates therefor, epoxy resin compn., molding material, and resin-sealed electronic device using the same)

IT Epoxy resins, preparation
 RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
 (cyclopentylene compds. and intermediates therefor, epoxy resin compn., molding material, and resin-sealed electronic device using the same)

IT **208344-52-9P 208344-55-2P 208344-59-6P 208344-60-9P**
 208344-63-2P 208344-64-3P
 RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM

(Technical or engineered material use); PREP (Preparation); USES (Uses)
(cyclopentylene compds. and intermediates therefor, epoxy resin compn.,
molding material, and resin-sealed electronic device using the same)

IT 78877-80-2P 78877-81-3P 100420-80-2P 100420-81-3P 208344-50-7P

208344-51-8P 208344-53-0P **208344-54-1P** 208344-56-3P

208344-57-4P 208344-58-5P 208344-61-0P 208344-62-1P

RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT
(Reactant or reagent)

(cyclopentylene compds. and intermediates therefor, epoxy resin compn.,
molding material, and resin-sealed electronic device using the same)

IT 29690-82-2, o-Cresol-epichlorohydrin-formaldehyde copolymer 89118-70-7,
Epikote YX-4000H

RL: POF (Polymer in formulation); TEM (Technical or engineered material
use); USES (Uses)

(cyclopentylene compds. and intermediates therefor, epoxy resin compn.,
molding material, and resin-sealed electronic device using the same)

IT 95-48-7, reactions 106-89-8, reactions 135-19-3, 2-Naphthol, reactions
542-92-7, Cyclopentadiene, reactions 576-26-1

RL: RCT (Reactant); RACT (Reactant or reagent)

(cyclopentylene compds. and intermediates therefor, epoxy resin compn.,
molding material, and resin-sealed electronic device using the same)

RE.CNT 23 THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Bartlett, P; Tetrahedron Letters 1985, V26(22), P2613 HCAPLUS
- (2) Farbenfabriken Bayer Ag; DE 1768930 A1 1972
- (3) Farbenfabriken Bayer Ag; FR 2013010 A1 1972 HCAPLUS
- (4) Farbenfabriken Bayer Ag; US 3689573 A 1972
- (5) Farbenfabriken Bayer Ag; JP 4714094 B1 1972
- (6) Farbenfabriken Bayer Ag; CH 514524 A 1972
- (7) Hitachi Chemical Co Ltd; JP 60135427 A 1985 HCAPLUS
- (8) Kanemasa, S; Tetrahedron Letters 1996, V37(47), P8505 HCAPLUS
- (9) Pirro d'Etude Therapeutiques; FR 2165741 A1 1973 HCAPLUS
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- (13) Rao, D; Tetrahedron Letters 1981, V22(25), P2337 HCAPLUS
- (14) Sumitomo Chemical Co Ltd; CA 1040213 A 1975 HCAPLUS
- (15) Sumitomo Chemical Co Ltd; DE 2431561 A1 1975 HCAPLUS
- (16) Sumitomo Chemical Co Ltd; US 3970694 A 1975 HCAPLUS
- (17) Sumitomo Chemical Co Ltd; JP 5024256 A 1975
- (18) Sumitomo Chemical Co Ltd; CH 602546 A 1975 HCAPLUS
- (19) Sumitomo Chemical Co Ltd; CH 603531 A 1975 HCAPLUS
- (20) Sumitomo Chemical Co Ltd; NO 7402207 A 1975 HCAPLUS
- (21) Sumitomo Chemical Co Ltd; SE 7408656 A 1975 HCAPLUS
- (22) Union Carbide Corp; US 3332908 A 1967 HCAPLUS
- (23) Union Carbide Corp; CA 863964 A 1967

IT **208344-52-9P 208344-55-2P**

RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM
(Technical or engineered material use); PREP (Preparation); USES (Uses)
(cyclopentylene compds. and intermediates therefor, epoxy resin compn.,
molding material, and resin-sealed electronic device using the same)

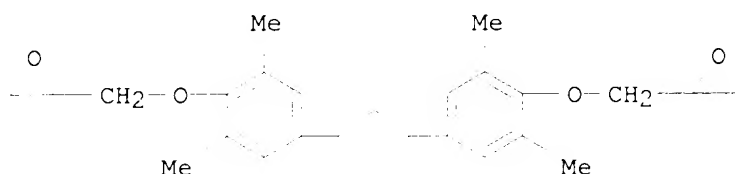
RN 208344-52-9 HCAPLUS

CN Oxirane, 2,2'-[1,3-cyclopentanediylbis[(2,6-dimethyl-4,1-
phenylene)oxymethylene]]bis-, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 208344-51-8

CMF C27 H34 O4



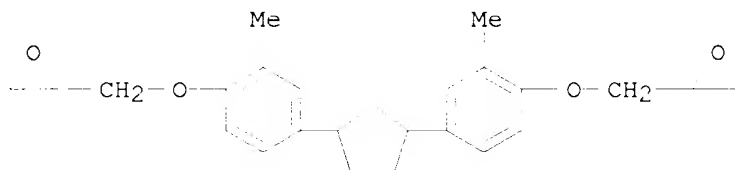
RN 208344-55-2 HCAPLUS

CN Oxirane, 2,2'-[1,3-cyclopentanediy]bis[(2-methyl-4,1-phenylene)oxymethylene]]bis-, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 208344-54-1

CMF C25 H30 O4



IT 208344-51-8P 208344-54-1P

RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent)

(cyclopentylene compds. and intermediates therefor, epoxy resin compn., molding material, and resin-sealed electronic device using the same)

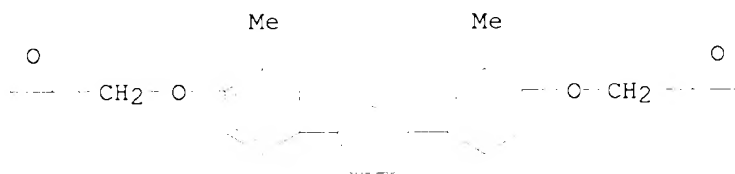
RN 208344-51-8 HCAPLUS

CN Oxirane, 2,2'-[1,3-cyclopentanediy]bis[(2,6-dimethyl-4,1-phenylene)oxymethylene]]bis- (9CI) (CA INDEX NAME)



RN 208344-54-1 HCAPLUS

CN Oxirane, 2,2'-[1,3-cyclopentanediy]bis[(2-methyl-4,1-phenylene)oxymethylene]]bis- (9CI) (CA INDEX NAME)



=> file hcaold

FILE 'HCAOLD' ENTERED AT 14:51:36 ON 18 MAR 2003

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FILE COVERS 1907-1966

FILE LAST UPDATED: 01 May 1997 (19970501/UP)

This file contains CAS Registry Numbers for easy and accurate substance identification. Title keywords, authors, patent assignees, and patent information, e.g., patent numbers, are now searchable from 1907-1966. TIFF images of CA abstracts printed between 1907-1966 are available in the PAGE display formats.

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=> s 123

L25 0 L23

not a Old reference